Electronic Patent Application Fee Transmittal							
Application Number:	10666399						
Filing Date:	18-Sep-2003						
Title of Invention:	MOLDED CHIP FABRICATION METHOD						
First Named Inventor/Applicant Name:	Mid	Michael S. Leung					
Filer:	Jaye G. Heybl/Joan Harriman						
Attorney Docket Number:	P0:	P0298US-7					
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Basic Filing:							
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